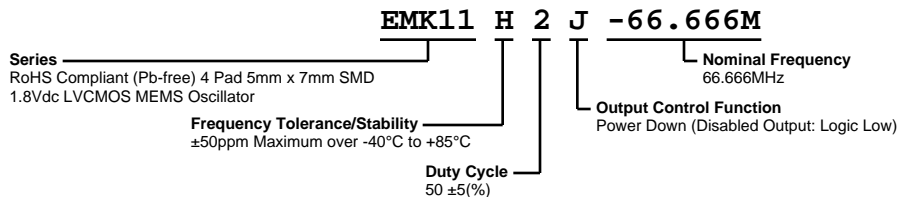


# EMK11H2J-66.666M



**ECLIPTEK**<sup>®</sup>  
CORPORATION



## ELECTRICAL SPECIFICATIONS

|  |  |
|--|--|
| <b>Nominal Frequency</b>               | 66.666MHz  |
| <b>Frequency Tolerance/Stability</b>   | ±50ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, 260°C Reflow, Shock, and Vibration) |
| <b>Aging at 25°C</b>                   | ±1ppm Maximum First Year   |
| <b>Operating Temperature Range</b>     | -40°C to +85°C   |
| <b>Supply Voltage</b>                  | 1.8Vdc ±5%   |
| <b>Input Current</b>                   | 18mA Maximum   |
| <b>Output Voltage Logic High (Voh)</b> | 90% of Vdd Minimum (IOH=-8mA)  |
| <b>Output Voltage Logic Low (Vol)</b>  | 10% of Vdd Maximum (IOL=+8mA)  |
| <b>Rise/Fall Time</b>                  | 2nSec Maximum (Measured from 20% to 80% of waveform)   |
| <b>Duty Cycle</b>                      | 50 ±5(%) (Measured at 50% of waveform)   |
| <b>Load Drive Capability</b>           | 15pF Maximum   |
| <b>Output Logic Type</b>               | CMOS   |
| <b>Output Control Function</b>         | Power Down (Disabled Output: Logic Low)  |
| <b>Output Control Input Voltage</b>    | +0.7Vdd Minimum or No Connect to Enable Output, +0.3Vdd Maximum to Disable Output  |
| <b>Standby Current</b>                 | 50µA Maximum (Disabled Output: Logic Low)  |
| <b>Peak to Peak Jitter (tPK)</b>       | 250pSec Maximum, 100pSec Typical   |
| <b>Start Up Time</b>                   | 50mSec Maximum   |
| <b>Storage Temperature Range</b>       | -55°C to +125°C  |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                                     |  |
|-------------------------------------|--|
| <b>ESD Susceptibility</b>           | MIL-STD-883, Method 3015, Class 2, HBM 2000V                       |
| <b>Flammability</b>                 | UL94-V0  |
| <b>Mechanical Shock</b>             | MIL-STD-883, Method 2002, Condition G, 30,000G                     |
| <b>Moisture Resistance</b>          | MIL-STD-883, Method 1004   |
| <b>Moisture Sensitivity Level</b>   | J-STD-020, MSL 1   |
| <b>Resistance to Soldering Heat</b> | MIL-STD-202, Method 210, Condition K                               |
| <b>Resistance to Solvents</b>       | MIL-STD-202, Method 215  |
| <b>Solderability</b>                | MIL-STD-883, Method 2003 (Four I/O Pads on bottom of package only) |
| <b>Temperature Cycling</b>          | MIL-STD-883, Method 1010, Condition B                              |
| <b>Thermal Shock</b>                | MIL-STD-883, Method 1011, Condition B                              |
| <b>Vibration</b>                    | MIL-STD-883, Method 2007, Condition A, 20G                         |

# EMK11H2J-66.666M

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION             |
|-----|------------------------|
| 1   | Power Down (Logic Low) |
| 2   | Ground                 |
| 3   | Output                 |
| 4   | Supply Voltage         |

| LINE | MARKING   |
|------|---|
| 1    | XXXX or XXXXX<br>XXXX or XXXXX=Ecliptek<br>Manufacturing Lot Code |

Note A: Center paddle is connected internally to oscillator ground (Pad 2).

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

## OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for CMOS Output



Note 1: An external 0.1 $\mu$ F low frequency tantalum bypass capacitor in parallel with a 0.01 $\mu$ F high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

|  |                                      |
|--|--------------------------------------|
| <b>T<sub>s</sub> MAX to T<sub>L</sub> (Ramp-up Rate)</b> | 3°C/second Maximum                   |
| <b>Preheat</b>   |                                      |
| - Temperature Minimum (T <sub>s</sub> MIN)               | 150°C                                |
| - Temperature Typical (T <sub>s</sub> TYP)               | 175°C                                |
| - Temperature Maximum (T <sub>s</sub> MAX)               | 200°C                                |
| - Time (t <sub>s</sub> MIN)                              | 60 - 180 Seconds                     |
| <b>Ramp-up Rate (T<sub>L</sub> to T<sub>p</sub>)</b>     | 3°C/second Maximum                   |
| <b>Time Maintained Above:</b>                            |                                      |
| - Temperature (T <sub>L</sub> )                          | 217°C                                |
| - Time (t <sub>L</sub> )                                 | 60 - 150 Seconds                     |
| <b>Peak Temperature (T<sub>p</sub>)</b>                  | 260°C Maximum for 10 Seconds Maximum |
| <b>Target Peak Temperature (T<sub>p</sub> Target)</b>    | 250°C +0/-5°C                        |
| <b>Time within 5°C of actual peak (t<sub>p</sub>)</b>    | 20 - 40 seconds                      |
| <b>Ramp-down Rate</b>                                    | 6°C/second Maximum                   |
| <b>Time 25°C to Peak Temperature (t)</b>                 | 8 minutes Maximum                    |
| <b>Moisture Sensitivity Level</b>                        | Level 1                              |

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

|  |  |
|--|--|
| <b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b> | 5°C/second Maximum                                     |
| <b>Preheat</b>   |  |
| - Temperature Minimum ( $T_S$ MIN)                             | N/A  |
| - Temperature Typical ( $T_S$ TYP)                             | 150°C  |
| - Temperature Maximum ( $T_S$ MAX)                             | N/A  |
| - Time ( $t_s$ MIN)  | 60 - 120 Seconds                                       |
| <b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>     | 5°C/second Maximum                                     |
| <b>Time Maintained Above:</b>                                  |  |
| - Temperature ( $T_L$ )  | 150°C  |
| - Time ( $t_L$ )   | 200 Seconds Maximum                                    |
| <b>Peak Temperature (<math>T_P</math>)</b>                     | 240°C Maximum  |
| <b>Target Peak Temperature (<math>T_P</math> Target)</b>       | 240°C Maximum 1 Time / 230°C Maximum 2 Times           |
| <b>Time within 5°C of actual peak (<math>t_p</math>)</b>       | 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time |
| <b>Ramp-down Rate</b>  | 5°C/second Maximum                                     |
| <b>Time 25°C to Peak Temperature (t)</b>                       | N/A  |
| <b>Moisture Sensitivity Level</b>                              | Level 1  |

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.